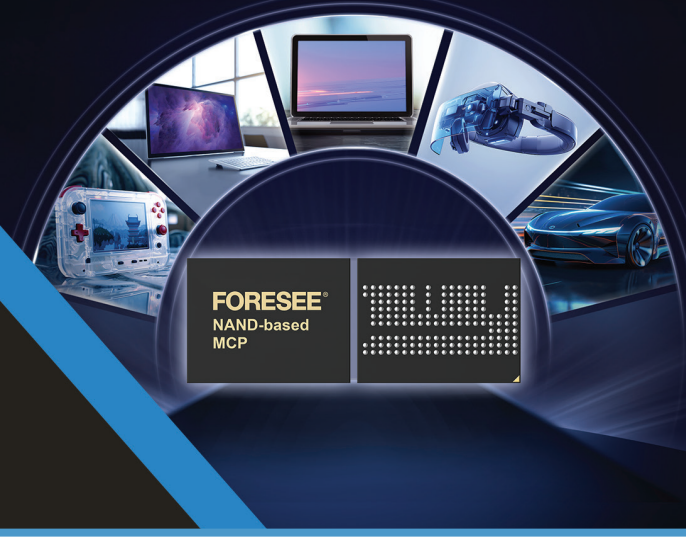
Lexar

ENTERPRISE

NAND-based MCP Industrial and Industrial Plus

Product Brief



Capacities

1Gb+1Gb, 2Gb+1Gb
2Gb+2Gb, 4Gb+2Gb,
4Gb+6Gb, 4Gb+8Gb
8Gb+6Gb, 8Gb+8Gb

Advanced Features

- Hardware WP# write protect
- Software block protect
- Unique ID
- One 2KB/4KB parameter page
- Sixty-two 2KB/4KB OTP pages
- Promised golden block0

Applications

- Mobile Phones
- 4G/5G Wireless Modules
- Digital Cameras
- Internet of Things (IoT) Devices
- Laptop Computers

High Performance, Minimal Power

The Lexar Enterprise NAND-based MCP Industrial and Industrial Plus is a dynamic device to use as a boot code source and DRAM in a single package. Thanks to an improved form factor, this device offers improved board space savings to optimize layout options and deliver a versatile, high capacity option tailor-made for mobile applications.

Key Benefits

An All-in-one Chip

SLC and LPDDR DRAM multi-chip package memory provides two-die in one package, delivering an all-in-one solution to support an optimized interface.

Fits in Tight Spaces

A minimal package footprint routes signals to a single component to provide an easier, efficient package footprint that provides excellent PCB space savings.

Optimized Power Efficiency

10mA is typical data for all the SLC NAND in the market, it couldn't be taken as special/optimized feature.

* Performance based on internal testing and may vary based on environmental conditions and usage. Specifications subject to change without notice.

Specifications

Product Series	Part Number	Capacity	NAND Flash	DRAM	Package	Operating Temperature[1]	Operating Voltage	Size
LPDDR2 NAND-based MCP	F70ME0101F-RWT	1Gb+1Gb	SLC NAND x8	LPDDR2 933 x32	FBGA162	-40°C to +85°C	NAND: 1.8V LPDDR2: VDDQ - 1.2V	10.5mm x 0.8mm
LPDDR2 NAND-based MCP	F70ME0201F-RWT	2Gb+1Gb	SLC NAND x8	LPDDR2 933 x32	FBGA162	-40°C to +85°C	NAND: 1.8V LPDDR2: VDDQ - 1.2V	10.5mm x 0.8mm
LPDDR2 NAND-based MCP	F70ME0202A-RWT	2Gb+2Gb	SLC NAND x8	LPDDR2 933 x32	FBGA162	-25°C to +85°C	NAND: 1.8V LPDDR2: VDDQ - 1.2V	10.5mm x 0.8mm
LPDDR2 NAND-based MCP	F70ME0402A-RWT	4Gb+2Gb	SLC NAND x8	LPDDR4/4x 4266 x16	FBGA162	-40°C to +85°C	NAND: 1.8V LPDDR2: VDDQ - 1.2V	10.5mm x 0.8mm
LPDDR4/4x NAND-based MCP	F70NH0406A-SWT	4Gb+6Gb	SLC NAND x8	LPDDR4/4x 4266 x16	WFB-GA149	-25°C to +85°C	NAND: 1.8V LPDDR4/4x: 1.1V, 0.6V	9.5mm x 0.8mm
LPDDR4/4x NAND-based MCP	F70NH0406A-SAT	4Gb+6Gb	SLC NAND x8	LPDDR4/4x 4266 x16	WFB-GA149	-40°C to +105°C	NAND: 1.8V LPDDR4/4x: 1.1V, 0.6V	9.5mm x 0.8mm
LPDDR4x NAND-based MCP	F70NH0408A-SWT	4Gb+8Gb	SLC NAND x8	LPDD4x 4266 x16	WFB-GA149	-25°C to +85°C	NAND: 1.8V LPDDR4/4x: 0.6V	9.5mm x 0.8mm
LPDDR4x NAND-based MCP	F70NH0408A-SAT	4Gb+8Gb	SLC NAND x8	LPDDR4x 4266 x16	WFB-GA149	-40°C to +105°C	NAND: 1.8V LPDDR4/4x: 0.6V	9.5mm x 0.8mm
LPDDR4/4x NAND-based MCP	F70NH0806A-SWT	8Gb+6Gb	SLC NAND x8	LPDDR4/4x 4266 x16	WFB-GA149	-25°C to +85°C	NAND: 1.8V LPDDR4/4x: 1.1V, 0.6V	9.5mm x 0.8mm
LPDDR4/4x NAND-based MCP	F70NH0806A-SAT	8Gb+6Gb	SLC NAND x8	LPDDR4/4x 4266 x16	136b FBGA	-40°C to +105°C	NAND: 1.8V LPDDR4/4x: 1.1V, 0.6V	9.5mm x 0.8mm
LPDDR4x NAND-based MCP	F70NH0808A-SWT	8Gb+8Gb	SLC NAND x8	LPDDR4x 4266 x16	WFB-GA149	-25°C to +85°C	NAND: 1.8V LPDDR4/4x: 0.6V	9.5mm x 0.8mm
LPDDR4x NAND-based MCP	F70NH0808A-SAT	8Gb+8Gb	SLC NAND x8	LPDDR4x 4266 x16	WFB-GA149	-40°C to +105°C	NAND: 1.8V LPDDR4/4x: 0.6V	9.5mm x 0.8mm

*Data based on internal testing. Actual performance may vary due to equipment differences.

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